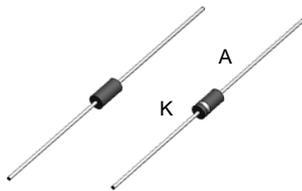


## 600 W TVS in DO-15



DO-15 (JEDEC DO-204AC)



Bidirectional



Unidirectional

## Features

- Peak pulse power:
  - 600 W (10/1000  $\mu$ s)
  - up to 4 kW (8/20  $\mu$ s)
- Stand-off voltage range from 5.8 V to 376 V
- Unidirectional and bidirectional types
- Operating  $T_j$  max: 175 °C
- High power capability at  $T_j$  max.: up to 420 W (10/1000  $\mu$ s)
- Lead finishing: matte tin plating

## Complies with the following standards

- UL94, V0
- J-STD-020 MSL level 1
- J-STD-002, JESD 22-B102 E3 and MIL-STD-750, method 2026
- JESD-201 class 2 whisker test
- UL 497B file number: QVGQ2.E136224
- IEC 61000-4-4 level 4:
  - 4 kV
- IEC 61000-4-2, C = 150 pF, R = 330  $\Omega$  exceeds level 4:
  - 30 kV (air discharge)
  - 30 kV (contact discharge)

## Description

The BZW06 TVS series is designed to protect sensitive equipment against electrostatic discharges according to IEC 61000-4-2, MIL STD 883 Method 3015, and electrical overstress such as IEC 61000-4-4 and 5. They are used for surges below 600 W 10/1000  $\mu$ s.

This planar technology makes it compatible with high-end equipment and SMPS where low leakage current and high junction temperature are required to provide reliability and stability over time.

## Product status link

BZW06-5V8,	BZW06-5V8B,
BZW06-15,	BZW06-15B,
BZW06-28,	BZW06-28B,
BZW06-31,	BZW06-31B,
BZW06-33,	BZW06-33B,
BZW06-58,	BZW06-58B,
BZW06-342,	BZW06-342B,
BZW06-376.	BZW06-376B.

# 1 Characteristics

Table 1. Absolute maximum ratings ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ )

Symbol	Parameter	Value	Unit	
$V_{PP}$	Peak pulse voltage	IEC 61000-4-2 (C = 150 pF, R = 330 $\Omega$ )		
		Contact discharge	30	kV
	Air discharge	30		
$P_{PP}$	Peak pulse power dissipation	10/1000 $\mu\text{s}$ , $T_j$ initial = $T_{amb}$	600	W
$I_{FSM}$	Non repetitive surge peak forward current for unidirectional types	$t_p = 10\text{ ms}$ , $T_j$ initial = $T_{amb}$	100	A
$T_{stg}$	Storage temperature range		-65 to +175	$^{\circ}\text{C}$
$T_j$	Operating junction temperature range		-55 to +175	$^{\circ}\text{C}$
$T_L$	Maximum lead temperature for soldering during 10 s at 5 mm from case		260	$^{\circ}\text{C}$

Figure 1. Electrical characteristics - parameter definitions

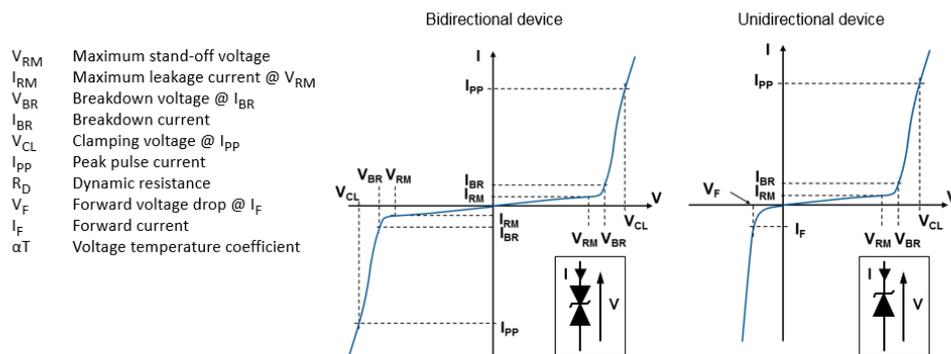
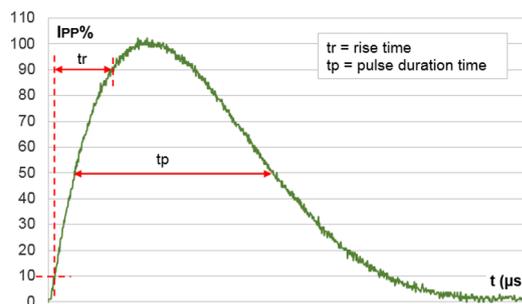


Figure 2. Pulse definition for electrical characteristics



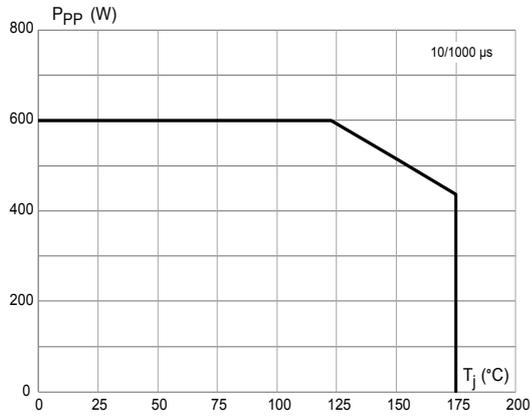
**Table 2. Electrical characteristics - parameter values ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)**

Type	$I_{RM}$ max at $V_{RM}$		$V_{BR}$ at $I_{BR}^{(1)}$				10 / 1000 $\mu\text{s}$			8 / 20 $\mu\text{s}$			$\alpha T$
							$V_{CL}^{(2)(3)}$	$I_{PP}^{(4)}$	$R_D$	$V_{CL}^{(2)(3)}$	$I_{PP}^{(4)}$	$R_D$	
	25 $^{\circ}\text{C}$		Min.	Typ.	Max.		Max.		Max.	Max.	Max.	Max.	
	$\mu\text{A}$	V	V			mA	V	A	$\Omega$	V	A	$\Omega$	$10^{-4}/^{\circ}\text{C}$
BZW06-5V8/B	20	5.8	6.45	6.8	7.14	10	10.5	57.0	0.059	13.4	298	0.021	5.7
BZW06-15/B	0.2	15	17.1	18	18.9	1	25.2	24.0	0.263	32.5	123	0.111	8.9
BZW06-28/B	0.2	28	31.4	33.1	34.8	1	45.7	13.1	0.835	59	68	0.357	9.8
BZW06-31/B	0.2	31	34.2	36	37.8	1	49.9	12.0	1.01	64.3	62	0.427	9.9
BZW06-33/B	0.2	33	37.1	39.1	41.1	1	53.9	11.1	1.16	69.7	57	0.503	10
BZW06-58/B	0.2	58	64.6	68	71.4	1	92.0	6.5	3.17	121	33	1.50	10.4
BZW06-342/B	0.2	342	380	400	420	1	548	1.1	116	706	6	50.2	11
BZW06-376/B	0.2	376	418	440	462	1	603	1	141	776	5.7	55.1	11

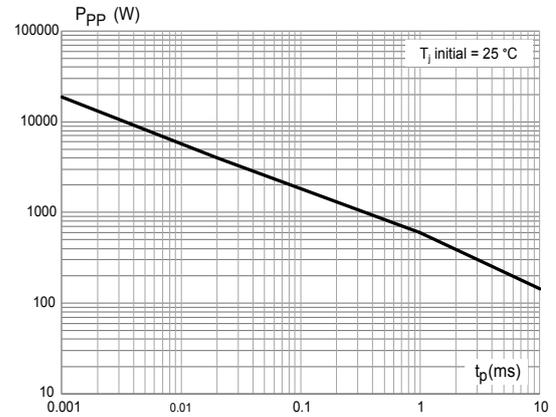
1. To calculate  $V_{BR}$  versus  $T_j$ :  $V_{BR}$  at  $T_j = V_{BR}$  at  $25\text{ }^{\circ}\text{C} \times (1 + \alpha T \times (T_j - 25))$
2. To calculate  $V_{CL}$  versus  $T_j$ :  $V_{CL}$  at  $T_j = V_{CL}$  at  $25\text{ }^{\circ}\text{C} \times (1 + \alpha T \times (T_j - 25))$
3. To calculate  $V_{CL}$  max versus  $I_{PPappli}$ :  $V_{CL}$  max =  $V_{BR}$  max. +  $R_D \times I_{PPappli}$
4. Surge capability given for both directions for unidirectional and bidirectional devices

## 1.1 Characteristics (curves)

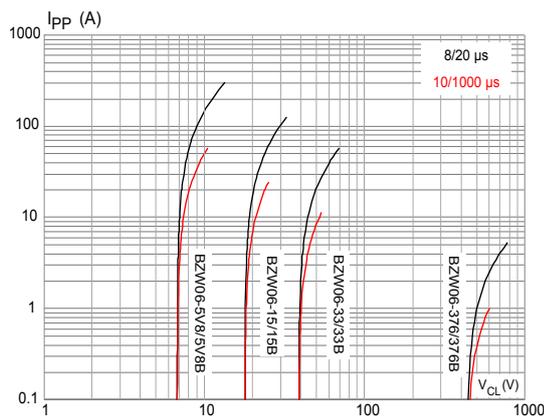
**Figure 3. Maximum peak power dissipation versus initial junction temperature**



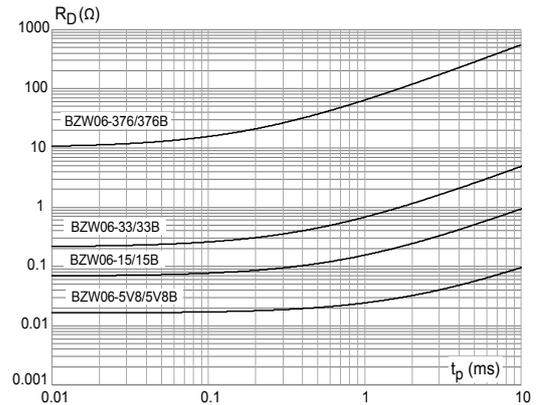
**Figure 4. Maximum peak pulse power versus exponential pulse duration**



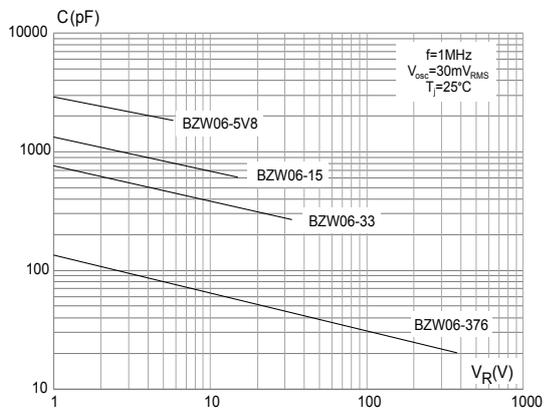
**Figure 5. Maximum peak pulse current versus clamping voltage**



**Figure 6. Dynamic resistance versus pulse duration**



**Figure 7. Junction capacitance versus reverse applied voltage (unidirectional type)**



**Figure 8. Junction capacitance versus applied voltage (bidirectional type)**

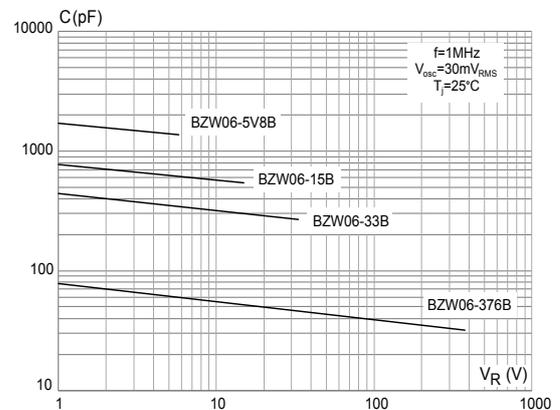


Figure 9. Leakage current versus junction temperature

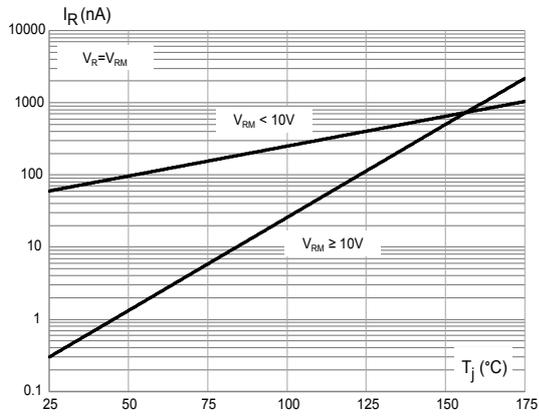


Figure 10. Peak forward voltage drop versus peak forward current

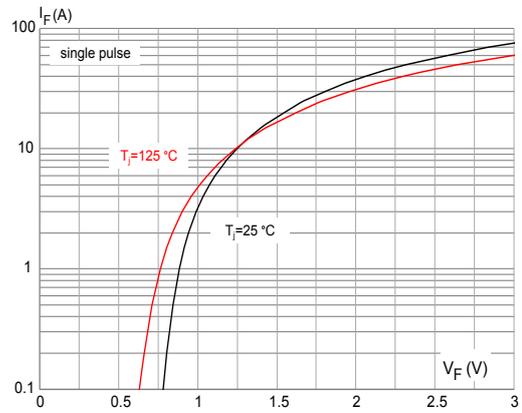


Figure 11. Thermal impedance junction to ambient versus pulse duration

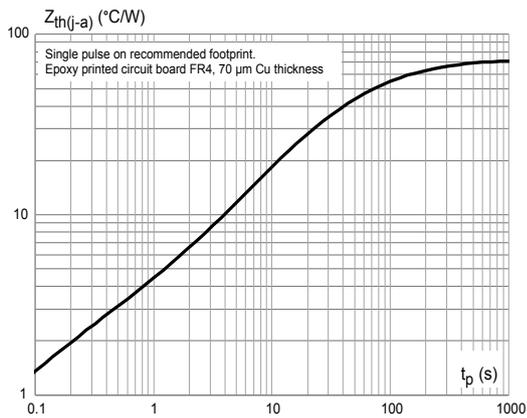
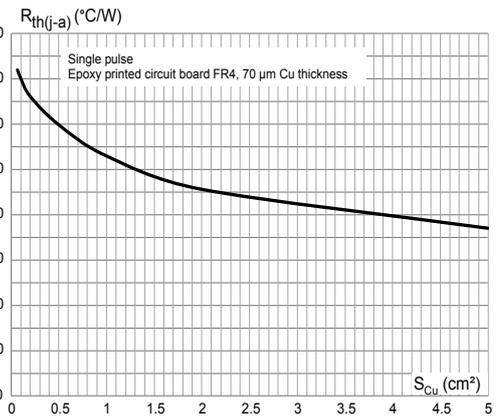


Figure 12. Thermal resistance junction to ambient versus copper area under each lead



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 DO-15 package information

Figure 13. DO-15 package outline

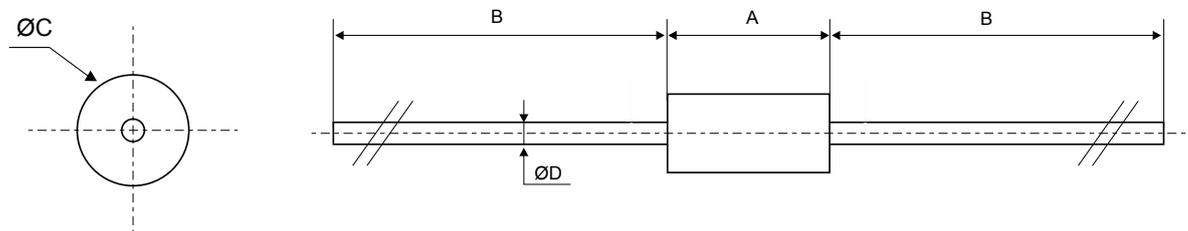


Table 3. DO-15 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.05	6.40	6.75	0.238	0.252	0.266
B	26.00	28.5	31.00	1.023	1.122	1.221
C	2.95	3.24	3.53	0.116	0.128	0.139
D	0.71	0.80	0.88	0.027	0.031	0.035

Figure 14. Marking layout

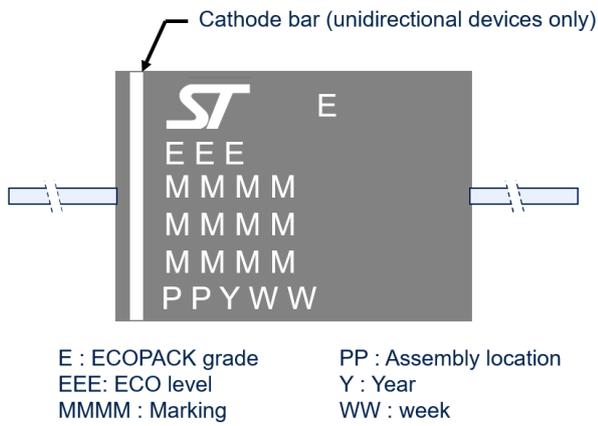


Figure 15. Tape and reel orientation

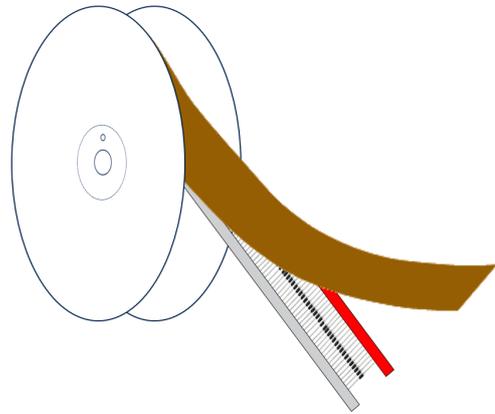


Figure 16. Reel dimension values (mm)

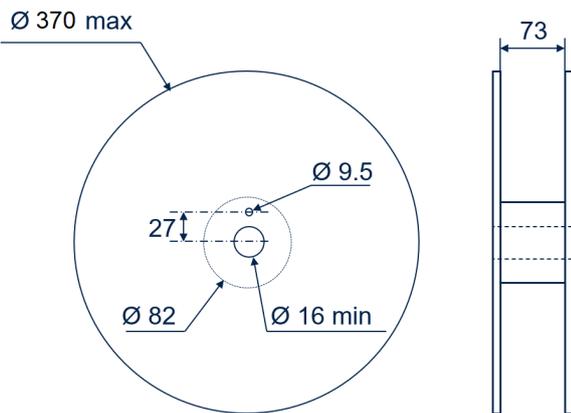


Figure 17. Inner box dimension values (mm)

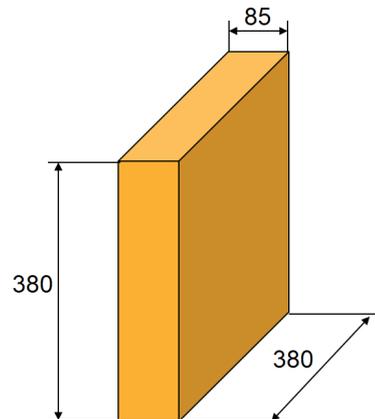


Figure 18. Ammopack dimension values (mm)

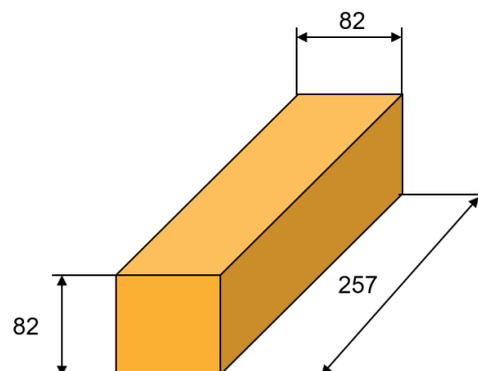
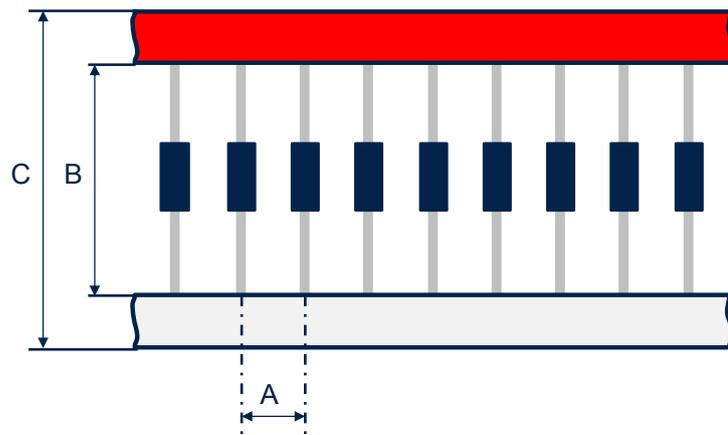


Figure 19. Tape outline



Dimensions are not to scale

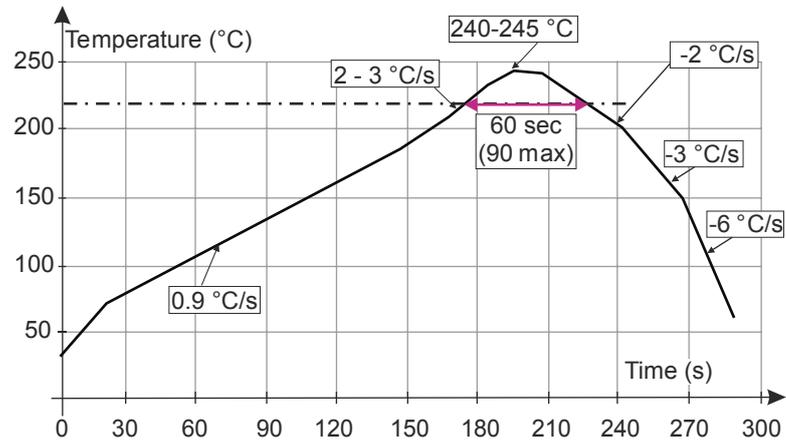
Unidirectional components are oriented with red tape on the cathode and white tape on the anode.  
Bidirectional components have red tape on both sides.

Table 4. Tape dimension values

Ref.	Dimensions		
	Millimeters		
	Min.	Typ.	Max.
A	4.5	5	5.5
B	51	53	55
C	62	65	68

## 2.2 Reflow profile

Figure 20. ST ECOPACK recommended soldering reflow profile for PCB mounting



**Note:** Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

For wave soldering profile refer to AN5088 chapter 1.5.

- [AN5088](#): Rectifiers thermal management, handling and mounting recommendations.

### 3 Ordering information

**Table 5. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
BZW06-xxRL/BZW06-xxBRL <sup>(1)</sup>	Equal to order code (without RL suffix)	DO-15	0.4 g	6000	Reel
P6KExxA/CA	Equal to order code			1000	Ammopack

1. Where xx corresponds to  $V_{RM}$  and blank or B indicates unidirectional or bidirectional version.

## Revision history

**Table 6. Document revision history**

Date	Revision	Changes
Feb-2003	3A	Last update.
06-Apr-2017	4	Updated Table 1, Table 3, Characteristics (curves) and DO-15 package information.
10-Jan-2023	5	Updated package information. Minor text changes.

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